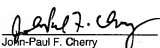


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	§	
Sun et al.	§	
	§	Group Art Unit: 1753
Serial No.: 10/616,097	§	
	§	
Confirmation No.: 1645	§	
	§	Examiner: Edna Wong
Filed: July 8, 2003	§	
	§	
For: Multiple-Step	§	
Electrodeposition Process	§	
for Direct Copper Plating	§	
on Barrier Materials	§	

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING OR TRANSMISSION	
I hereby certify that this correspondence is being deposited on with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Missing Parts, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, or electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of the Commissioner for Patents, on the date shown below.	
September 15, 2006 Date	 John-Paul F. Cherry

Dear Sir:

**RESPONSE TO OFFICE ACTION DATED MAY 15, 2006**

In response to the Office Action dated May 15, 2006, having a shortened statutory period for response extended by one month and set to expire on September 15, 2006, please enter this Response and reconsider the claims pending in the application for reasons discussed below. Transmitted with this Response is a Petition for Extension of Time and the authority to charge fees. Although the Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/008241/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**Amendments to the Claims** begin on page 2 of this paper. **Remarks** begin on page 8 of this paper.